

# D1FT6

## Schottky Barrier Diodes 60V, 2A

### Feature

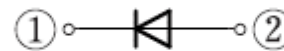
- Small SMD
- Tj=175°C
- Ultra low I<sub>R</sub>
- Based on AEC-Q101
- Pb free terminal
- RoHS:Yes

### OUTLINE

Package (House Name): 1F  
Package (JEDEC Code): DO-214AC



### Equivalent circuit



### Absolute Maximum Ratings (unless otherwise specified : Tl=25°C)

Item	Symbol	Conditions	Ratings	Unit
Storage temperature	T <sub>stg</sub>		-55 to 175	°C
Junction temperature	T <sub>j</sub>		-55 to 175	°C
Repetitive peak reverse voltage	V <sub>RRM</sub>		60	V
Average forward current	I <sub>F(AV)</sub>	50Hz sine wave, Resistance load, Tl=141°C	2	A
Average forward current	I <sub>F(AV)</sub>	50Hz sine wave, Resistance load, On alumina substrate, Ta=25°C ※	1.94	A
Average forward current	I <sub>F(AV)</sub>	50Hz sine wave, Resistance load, On glass-epoxy substrate, Ta=25°C ※	1.45	A
Surge forward current	I <sub>FSM</sub>	50Hz sine wave, Non-repetitive, 1cycle, Peak value, Tj=25°C	60	A

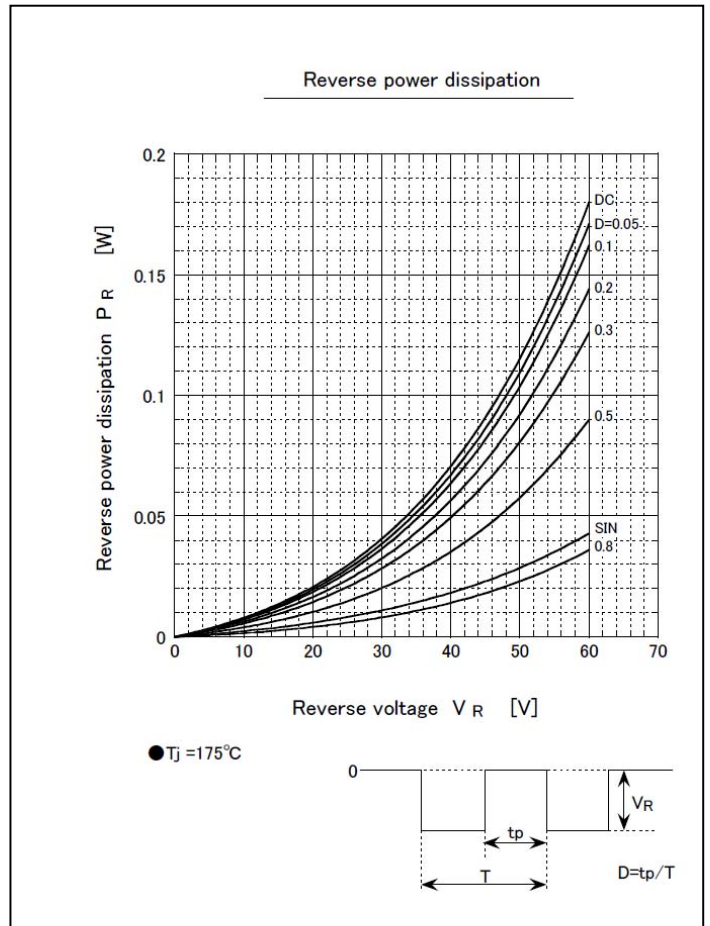
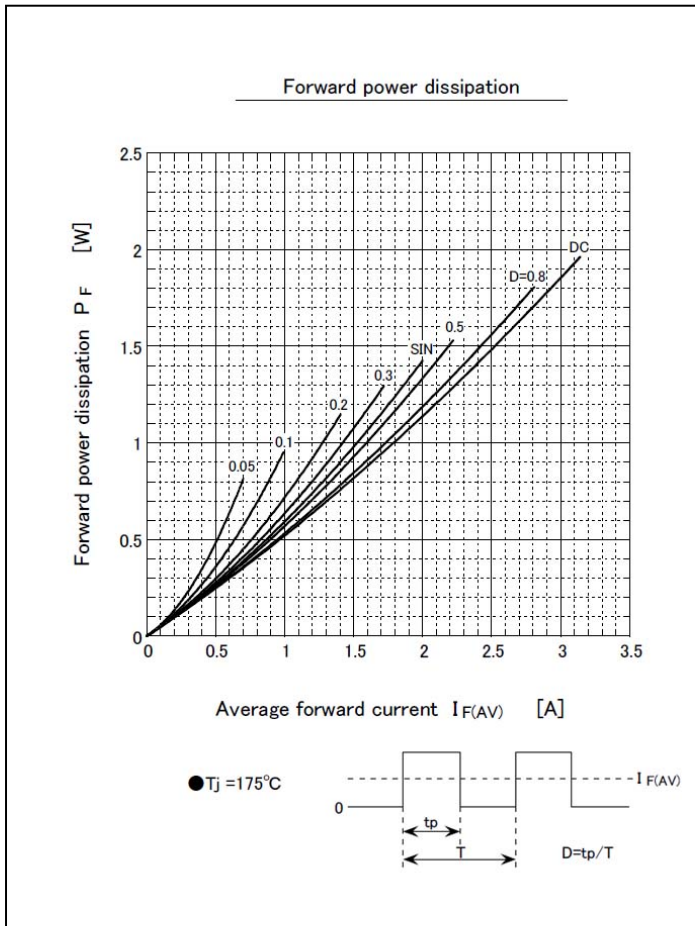
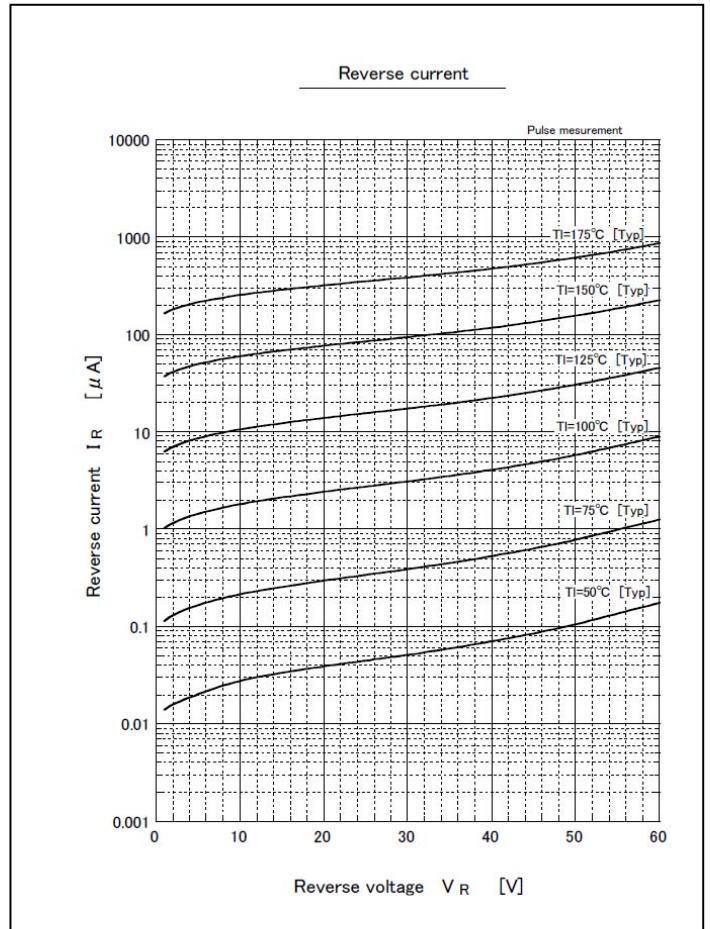
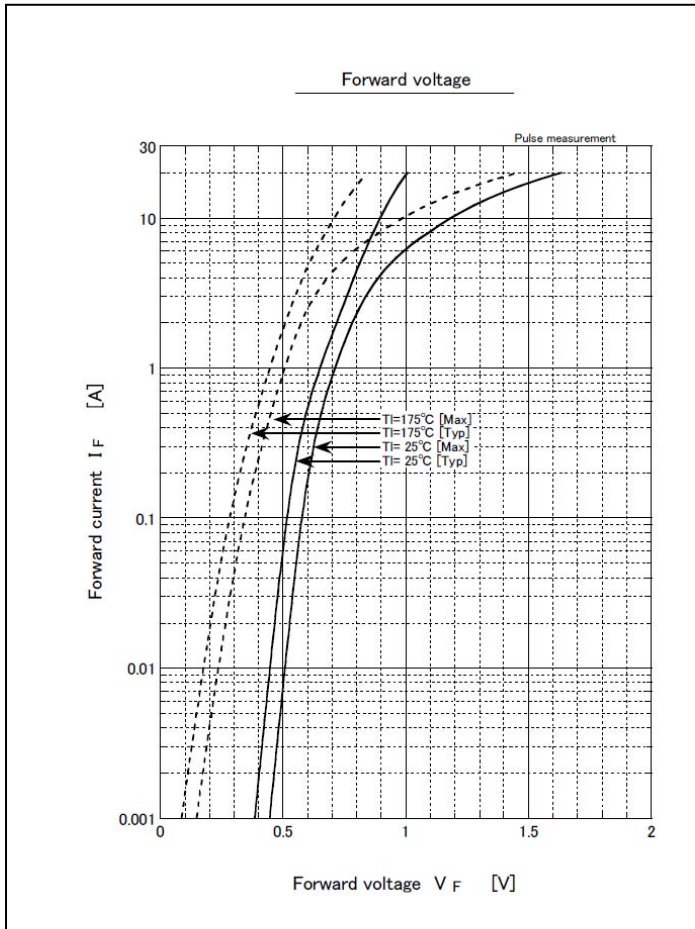
※ :See the original Specifications

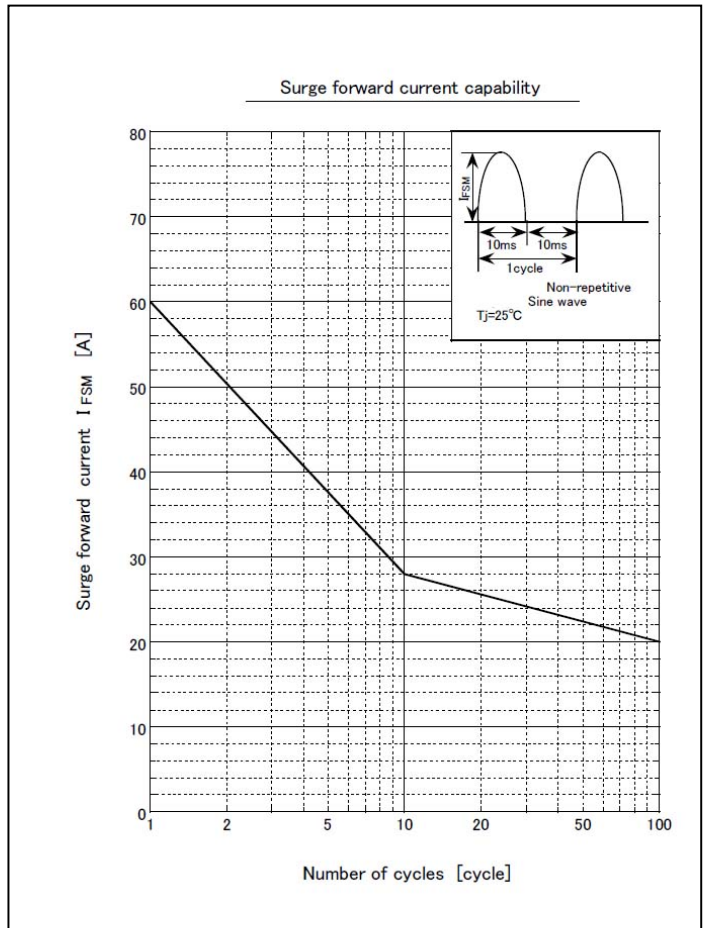
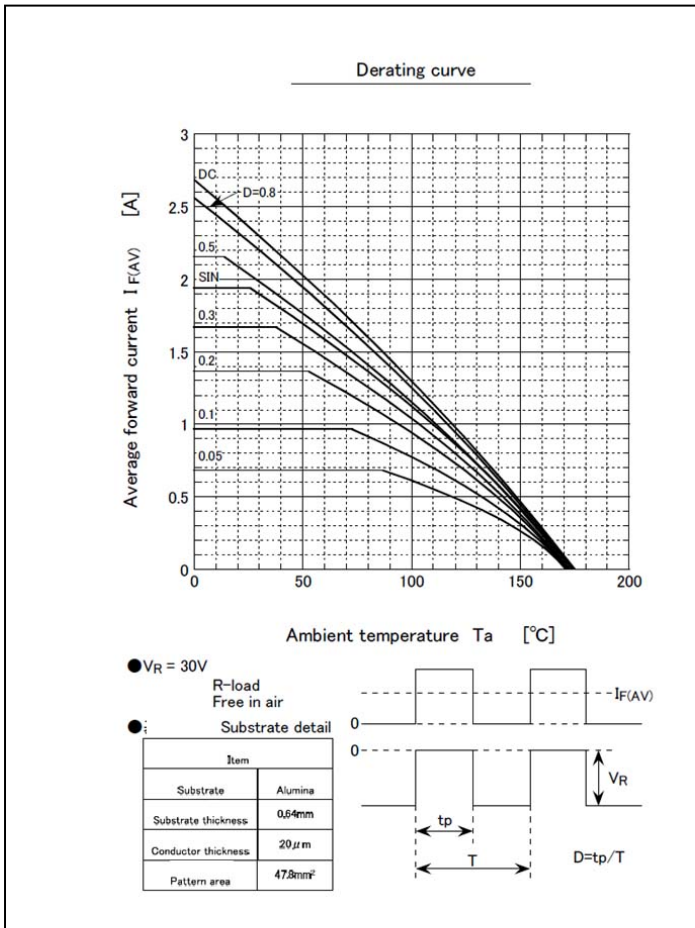
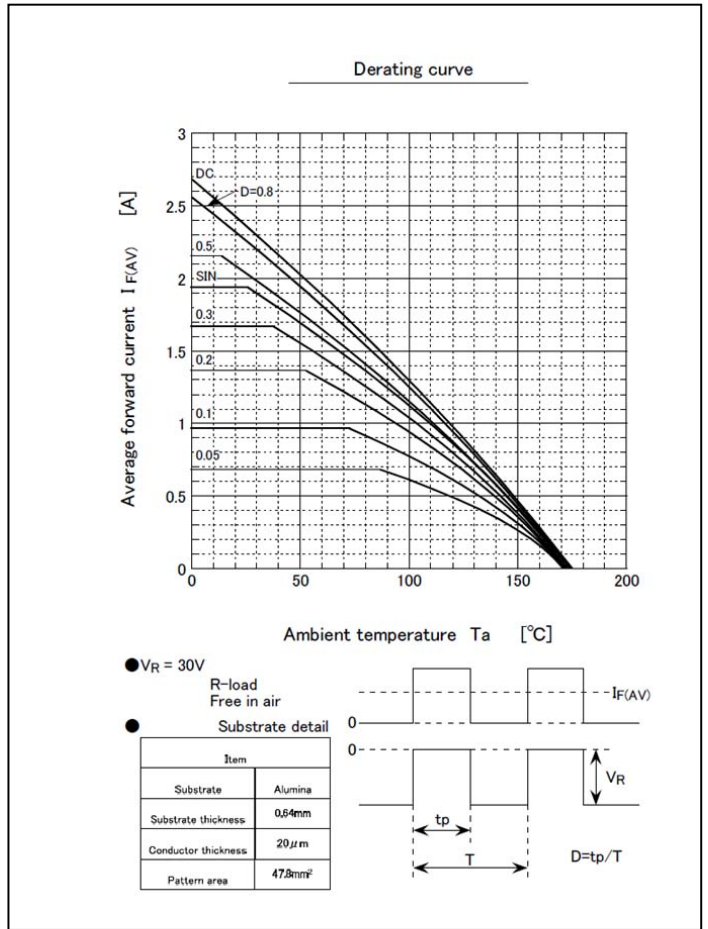
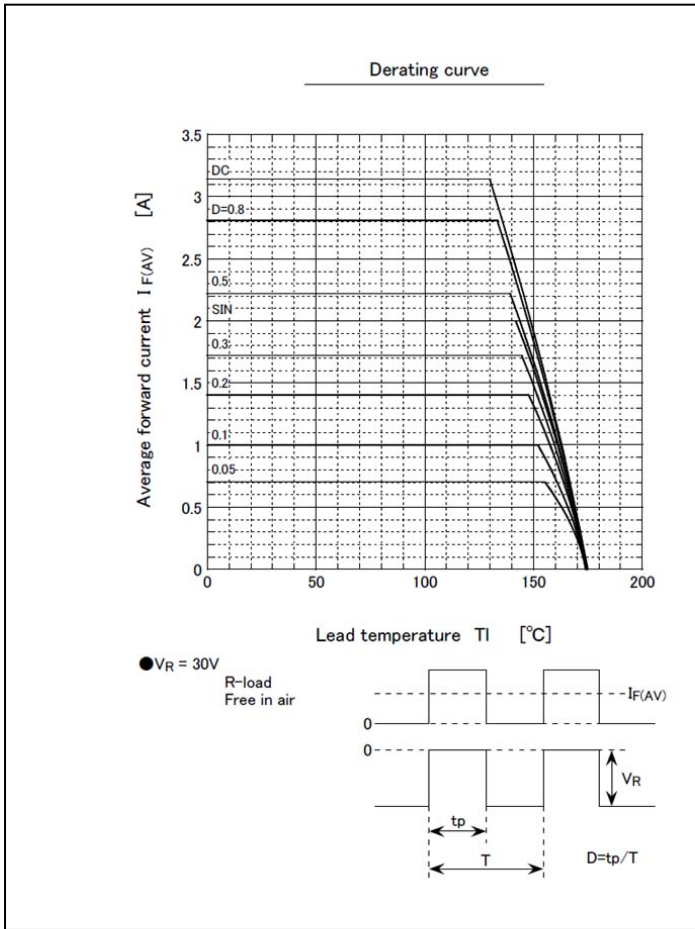
**Electrical Characteristics** (unless otherwise specified : Tl=25°C)

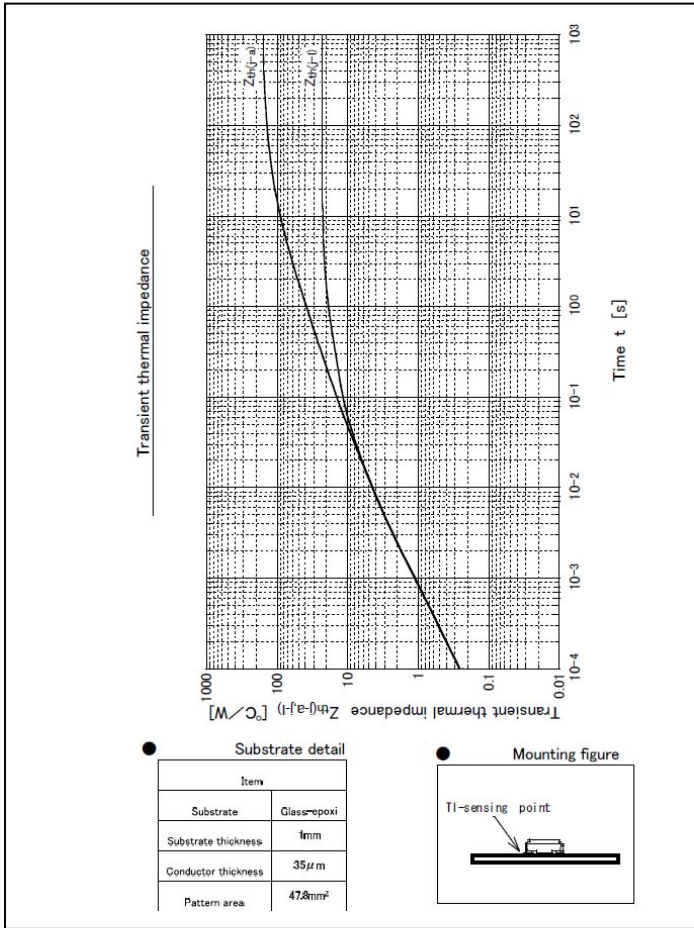
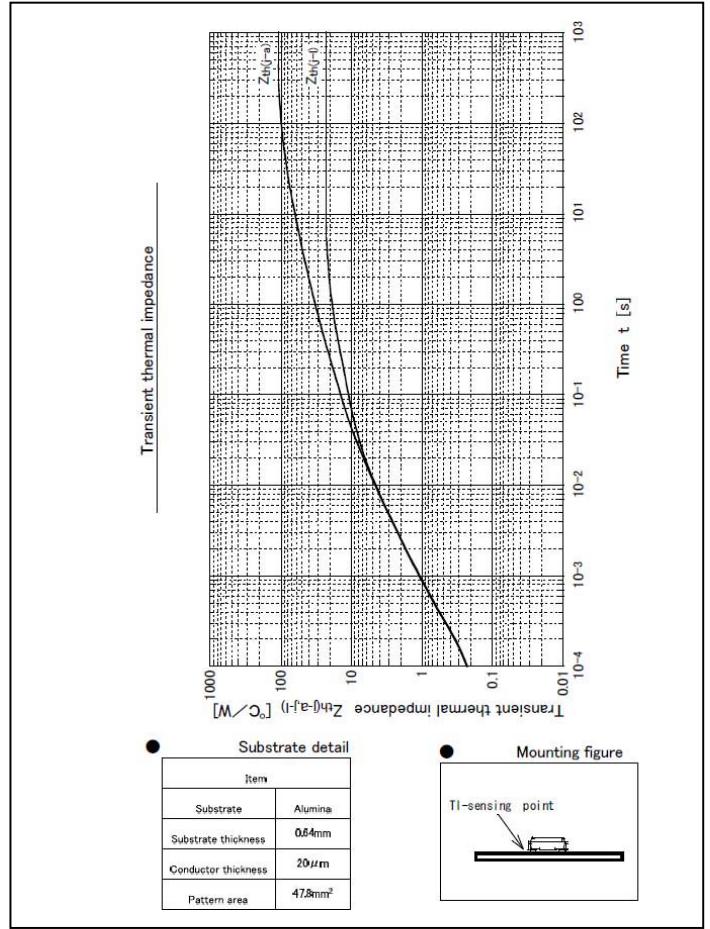
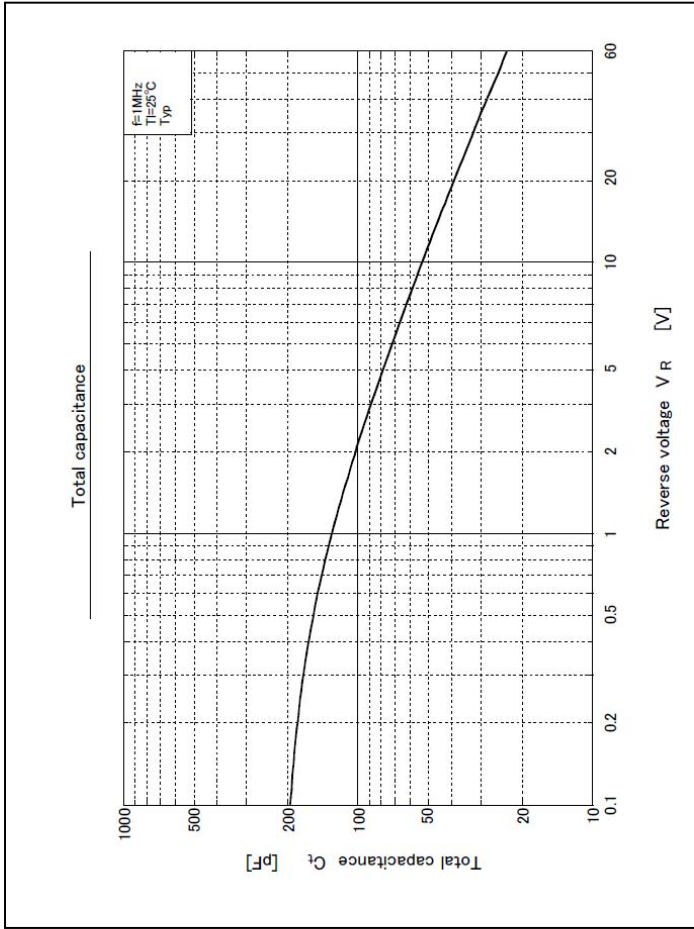
Item	Symbol	Conditions	Ratings			Unit
			MIN	TYP	MAX	
Forward voltage	$V_F$	IF=2.0A, Pulse measurement			0.78	V
Forward voltage	$V_F$	IF=1.0A, Pulse measurement			0.71	V
Reverse current	$I_R$	VR=60V, Pulse measurement			0.005	mA
Total capacitance	$C_t$	f=1MHz, VR=10V		53		pF
Thermal resistance	Rth(j-l)	Junction to lead			23	°C/W
Thermal resistance	Rth(j-a)	Junction to ambient, On alumina substrate ※			108	°C/W
Thermal resistance	Rth(j-a)	Junction to ambient, On glass-epoxy substrate ※			157	°C/W

※ :See the original Specifications

# CHARACTERISTIC DIAGRAMS







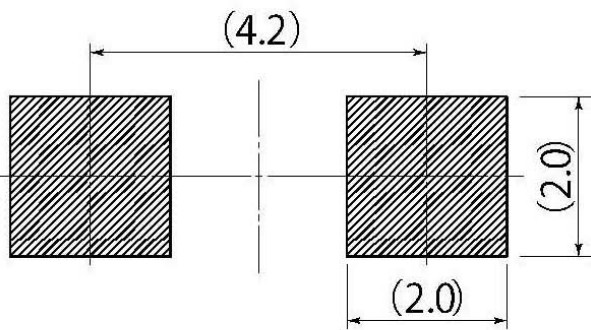
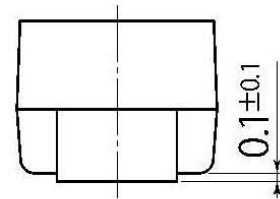
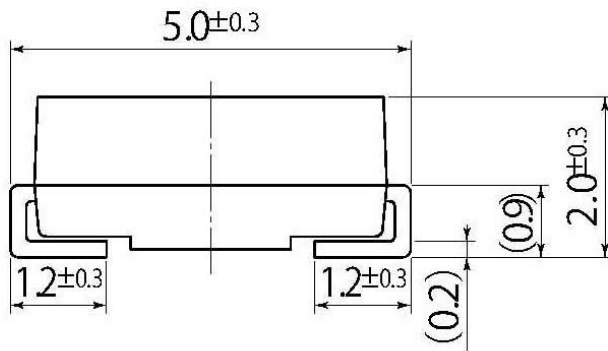
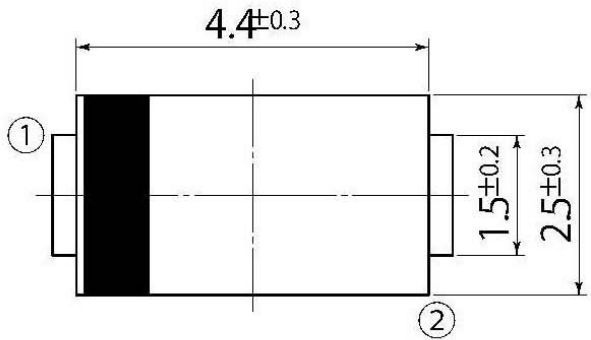
# Outline Dimensions

unit:mm

scale: 10/1

B3

JEDEC Code	DO-214AC
JEITA Code	—
House Name	1F, CF



Referential Soldering Pad

• Optimize soldering pad to the board design and soldering condition.

## Notes

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